

Microsemi Corporation

January 6, 2017

Product/Process Change Notification No: PCN1671

Change Classification: Major

Subject: Microsemi AGLP Family Gold-to-Copper Conversion

Description of Change: Microsemi IGLOO® PLUS (AGLP) devices are now qualified for CS289/CSG289 packaging using PCC wire. These devices are fabricated at United Microelectronics Corporation (UMC) and assembled at the UTAC Dongguan (UDG), China facility. Die size is 3.94 mm x 3.077 mm.

Reason for Change

Conversion to PCC wire is aligned with the current industry trend. Our assembly vendor has extensive experience in copper bond wire assembly. Copper bond wire, which is used in high-volume production by our assembly vendor, has demonstrated equal electrical and mechanical performance to gold wire.

Application Impact

Products assembled with copper bond wire have no changes in the moisture sensitivity level (MSL), functionality, performance, quality, reliability and in the thermal and electrical performance of the device.

Products Affected by this Change

IGLOO Plus FPGAs		
AGLP125V2-CS289	AGLP060V2-CS289	AGLP030V2-CS289
AGLP125V2-CS289I	AGLP060V2-CS289I	AGLP030V2-CS289I
AGLP125V2-CSG289	AGLP060V2-CSG289	AGLP030V2-CSG289
AGLP125V2-CSG289I	AGLP060V2-CSG289I	AGLP030V2-CSG289I
AGLP125V5-CS289	AGLP060V5-CS289	AGLP030V5-CS289
AGLP125V5-CS289I	AGLP060V5-CS289I	AGLP030V5-CS289I
AGLP125V5-CSG289	AGLP060V5-CSG289	AGLP030V5-CSG289
AGLP125V5-CSG289I	AGLP060V5-CSG289I	AGLP030V5-CSG289I

Production Shipment Schedule

Microsemi may begin shipping the devices with PCC wire starting **April 5, 2017**.

Microsemi reserves the right to continue the shipment of devices with gold (Au) wire following the change implementation date. Following the change implementation, customers may receive a mix of pre-conversion (Au wire) products and products with PCC wire.

Qualification Data

The qualification report is available upon request.

Contact Information:

If you have further questions about this topic, contact Microsemi's Technical Support at soc_tech@microsemi.com.

Regards,

Microsemi Corporation

Any projected dates in this PCN are based on the most current product information at the time this PCN is being issued, but they may change due to unforeseen circumstances. For the latest schedule and any other information, please contact your local Microsemi Sales Office, the factory contact shown above, or your local distributor.

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